

**Committee Details (ENVELOPE –I)**

**Tender ID: 2026\_AAI\_ 277705 \_1**

**Name of Work: Repair of damaged pavement joints with Polysulphide sealing compound after removal of damaged sealants, repair of joint cracks and small potholes on Runway, Taxiway, Apron and allied locations at Tezu Airport.**

| <b>Sl. No.</b> | <b>Name</b>          | <b>Designation</b> | <b>Response</b>                                    |
|----------------|----------------------|--------------------|----------------------------------------------------|
| 1.             | Sh. Arup Hatibaruah  | AGM(E-C)           | Committee Chairperson, Bid Manager, Bid Evaluator. |
| 2              | Sh. Chittaranjan Das | Mgr(E-C)           | Bid Evaluator                                      |
| 3              | Sh. Ajit Dutta       | AGM(Fin)           | Bid Opener                                         |

04 nos. of bidder have been accepted out of 04 nos. of bidder in Envelope-I (Technical evaluation) and recommended for financial bid opening (Envelope-II).

**Signature Not Verified**

Digitally signed by ARUP HATIBARUAH  
Date: 2026.07.02 17:05:44 IST  
Location: eProcurement System for  
Central PSUs